

Title (en)
COOLED INTEGRATED CIRCUIT

Title (de)
GEKÜHLTE INTEGRIERTE SCHALTUNG

Title (fr)
CIRCUIT INTEGRE REFROIDI

Publication
EP 1787326 A1 20070523 (DE)

Application
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Priority
DE 2004001577 W 20040720

Abstract (en)
[origin: WO2006007803A1] The invention relates to an integrated circuit (1) having a plurality of substrate layers (2), active and/or passive components (3) embedded in the substrate layers (2), high-frequency lines conducted to the components (3) through the substrate layers (2), and cooling channels (6) for the dissipation of heat. The inventive circuit is characterized in that the cooling channels (6) are configured as high-frequency lines.

IPC 8 full level
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CPC (source: EP US)
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See references of WO 2006007803A1

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